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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/748,274	12/31/2003	Masanori Minamio	60188-692	6600

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EXAMINER

WILLIAMS, ALEXANDER O

ART UNIT	PAPER NUMBER
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2826

DATE MAILED: 06/30/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

10/748,274

Applicant(s)

MINAMIO ET AL.

Examiner

Alexander O. Williams

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 18 April 2005.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-5 and 10 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-5 and 10 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☒ None of:
- 1) ☒ Certified copies of the priority documents have been received.
 - 2) ☐ Certified copies of the priority documents have been received in Application No. _____.
 - 3) ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date _____.
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____.
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____.

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Serial Number: 10/748274 Attorney's Docket #: 60188-692
Filing Date: 12/31/03; claimed foreign priority to 12/5/01

Applicant: Minamio et al.

Examiner: Alexander Williams

Applicant's Amendment filed 4/18/05 has been acknowledged.

Applicant's Drawing correction filed 4/18/05 has been acknowledged and accepted.

Claims 6-9 have been canceled.

This application is a divisional application of serial number 10/230297, filed 8/29/02.

Acknowledgment is made of applicant's claim for foreign priority based on an application filed in Japan on 12/5/2001. It is noted, however, that applicant has not filed a certified copy of the foreign application as required by 35 U.S.C. 119(b).

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains.

Patentability shall not be negated by the manner in which the invention was made.

This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein

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were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(f) or (g) prior art under 35 U.S.C. 103(a).

Initially, and with respect to claims 1 and 10, note that a "product by process" claim is directed to the product per se, no matter how actually made, In re Hirao, 190 USPQ 15 at 17 (footnote 3). See also In re Brown, 173 USPQ 685; In re Luck, 177 USPQ 523; In re Wertheim, 191 USPQ 90 (209 USPQ 554 does not deal with this issue); In re Fitzgerald, 205 USPQ 594, 596 (CCPA); In re Marosi et al., 218 USPQ 289 (CAFC); and most recently, In re Thorpe et al., 227 USPQ 964 (CAFC, 1985) all of which make it clear that it is the final product per se which must be determined in a "product by process" claim, and not the patentability of the process, and that, as here, an old or obvious product produced by a new method is not patentable as a product, whether claimed in "product by process" claims or not. Note that Applicant has burden of proof in such cases as the above case law makes clear.

Claims 1, 2, 5 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Shimaniki (U.S. Patent Application Publication # 2003/0001249 A1).

1. Shimanuki (figures 1 to 64) specifically figures 10(e) and 12 show a resin-encapsulated semiconductor device, comprising: a die pad **5** provided by removing a lower portion of a lead frame; a semiconductor chip **8** mounted on the die pad; a plurality of leads **2** provided by removing an upper portion of the lead frame; a connection member **10** for connecting the semiconductor chip and the lead with each other; a plurality of suspension leads **4** connected to the die pad; and an encapsulation resin **11** for encapsulating therein the die pad, the semiconductor chip, the leads, the connection member and the suspension leads, with a bottom surface and an outer side surface of each lead (**any portion of the leads outside**

of the resin 11) being exposed as an external terminal, wherein: an upper surface **(top of 5)** of the die pad is located higher than an upper surface **(top of 2)** of the lead; a lower surface **(bottom of 5)** of the die pad is located higher than a lower surface **(bottom of 2)** of the lead; and the suspension leads are not bent in a bending process. Note: The Examiner is interested in finding the final structure claimed by Applicant. The process or steps performed to get to the final claimed structure in given little weight in the examination of the claims.

2. The resin-encapsulated semiconductor device of claim 1, Shimanuki show wherein: the semiconductor chip is mounted with its principal surface facing up **(top of 8)**; and the connection member is a thin metal wire.

5. The resin-encapsulated semiconductor device of claim 1, Shimanuki show wherein at least a portion of each of the die pad and the lead has a thickness of 100 micrometers to 150 micrometers **(page 12, paragraph [0192])**. Note that the specification contains no disclosure of either the critical nature of the claimed dimensions or any unexpected results arising therefrom. Where patentability is said to be based upon particular chosen dimensions or upon another variable recited in a claim, the Applicant must show that the chosen dimensions are critical. In re Woodruff, 919 F.2d 1575, 1578, 16 USPQ2d 1934, 1936 (Fed. Cir. 1990).

As to the grounds of rejection under section 103, see MPEP § 2113.

Claims 1, 2 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaguchi (Japan Patent # 11-260990).

1. Yamaguchi (figures 1 to 20) specifically figure 1 show a resin-encapsulated semiconductor device, comprising: a die pad **13** provided by removing a lower portion **13b** of a lead frame; a semiconductor chip **15** mounted on the die pad; a plurality of leads **18** provided by removing an upper portion **12** of the lead frame; a connection member **16**

for connecting the semiconductor chip and the lead with each other; a plurality of suspension leads **14,45** connected to the die pad; and an encapsulation resin **17** for encapsulating therein the die pad, the semiconductor chip, the leads, the connection member and the suspension leads, with a bottom surface and an outer side surface of each lead being exposed as an external terminal, wherein: an upper surface of the die pad is located higher than an upper surface of the lead; a lower surface of the die pad is located higher than a lower surface of the lead; and the suspension leads are not bent in a bending process. Note: The Examiner is interested in finding the final structure claimed by Applicant. The process or steps performed to get to the final claimed structure in given little weight in the examination of the claims.

2. The resin-encapsulated semiconductor device of claim 1, Yamaguchi show wherein: the semiconductor chip is mounted with its principal surface facing up; and the connection member is a thin metal wire.

As to the grounds of rejection under section 103, see MPEP § 2113.

Claims 1, 3, 4 and 10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wu (U.S. Patent # 6,661,087 B2).

1. Wu (figures 1 to 7) specifically figure 4 show a resin-encapsulated semiconductor device **3**, comprising: a die pad **31** provided by removing a lower portion of a lead frame; a semiconductor chip **33** mounted on the die pad; a plurality of leads **32** provided by removing an upper portion of the lead frame; a connection member **34** for connecting the semiconductor chip and the lead with each other; a plurality of suspension leads (**inherit**) connected to the die pad; and an encapsulation resin **35** for encapsulating

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therein the die pad, the semiconductor chip, the leads, the connection member and the suspension leads, with a bottom surface and an outer side surface of each lead being exposed as an external terminal, wherein: an upper surface of the die pad is located higher than an upper surface of the lead; a lower surface of the die pad is located higher than a lower surface of the lead; and the suspension leads are not bent in a bending process. Note: The Examiner is interested in finding the final structure claimed by Applicant. The process or steps performed to get to the final claimed structure in given little weight in the examination of the claims.

3. The resin-encapsulated semiconductor device of claim 1, Wu show wherein: the semiconductor chip is mounted with its principal surface facing down; and the connection member is a bump **34** made of a metal.

4. The resin-encapsulated semiconductor device of claim 1, Wu show wherein at least a portion of the semiconductor chip overlaps with the lead **32,322** as viewed from above.

As to the grounds of rejection under section 103, see MPEP § 2113.

Response

Applicant's arguments filed 4/18/05 has been fully considered, but are moot in view of the new grounds of rejections detailed above.

The insertion of Applicant's additional claimed language, for example, "in claim 1 and new claim 10" cause for further search and consideration to make this action final.

Applicant's amendment necessitated the new grounds of rejection. Accordingly, **THIS ACTION IS MADE FINAL**. See M.P.E.P. § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 C.F.R. § 1.136(a).

A SHORTENED STATUTORY PERIOD FOR RESPONSE TO THIS FINAL ACTION IS SET TO EXPIRE THREE MONTHS FROM THE DATE OF THIS ACTION.

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IN THE EVENT A FIRST RESPONSE IS FILED WITHIN TWO MONTHS OF THE MAILING DATE OF THIS FINAL ACTION AND THE ADVISORY ACTION IS NOT MAILED UNTIL AFTER THE END OF THE THREE-MONTH SHORTENED STATUTORY PERIOD, THEN THE SHORTENED STATUTORY PERIOD WILL EXPIRE ON THE DATE THE ADVISORY ACTION IS MAILED, AND ANY EXTENSION FEE PURSUANT TO 37 C.F.R. § 1.136(a) WILL BE CALCULATED FROM THE MAILING DATE OF THE ADVISORY ACTION. IN NO EVENT WILL THE STATUTORY PERIOD FOR RESPONSE EXPIRE LATER THAN SIX MONTHS FROM THE DATE OF THIS FINAL ACTION.

The listed references are cited as of interest to this application, but not applied at this time.

Field of Search	Date
U.S. Class and subclass: 257/684,796,696,698,874,786,678,692,693,676,666,787	1/11/05 6/22/05
Other Documentation: foreign patents and literature in 257/684,796,696,698,874,786,678,692,693,676,666,787	1/11/05 6/22/05
Electronic data base(s): U.S. Patents EAST	1/11/05

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30-7:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Alexander O Williams
Primary Examiner
Art Unit 2826

AOW
6/22/05